2020-3-18 Rev.1.0

TOSHIBA

RD Number: RD192

RD Title: TB67H451FNG Evaluation Circuit BOM

| Item No. | Designator | Quantity | Value | Part Number | Manufacturer | Description | Package | Not Mount |
|----------|------------|----------|----------------|-------------|--------------|--------------------------------|---------|-----------|
| 1 | CN1 | 1 | Terminal block | _ | _ | PCB terminal block 2 positions | | |
| 2 | CN2 | 1 | Terminal block | _ | _ | PCB terminal block 2 positions | | |
| 3 | CVCC | 1 | 1μF 10V | _ | _ | Chip capacitor | | |
| 4 | CVM1 | 1 | 1μF 50V | _ | _ | Chip capacitor | | |
| 5 | CVM2 | 1 | 100μF 50V | _ | _ | Electrolytic capacitor | | |
| 6 | CVREF | 1 | 0.1µF 10V | _ | _ | Chip capacitor | | |
| 7 | IC1 | 1 | TB67H451FNG | TB67H451FNG | TOSHIBA | DC Brushed Motor Driver IC | HSOP8 | |
| 8 | JP1 | 1 | 3 pin header | _ | _ | Pin header 3P | | |
| 9 | JP2 | 1 | 3 pin header | _ | _ | Pin header 3P | | |
| 10 | JP3 | 1 | 3 pin header | _ | _ | Pin header 3P | | |
| 11 | R1 | 0 | Not mount | _ | _ | Chip resistor | | ✓ |
| 12 | R2 | 0 | Not mount | _ | _ | Chip resistor | | ✓ |
| 13 | RRS1 | 1 | 0.22Ω 1W | _ | _ | Chip resistor | | |
| 14 | RRS2 | 1 | 0.22Ω 1W | _ | _ | Chip resistor | | |
| 15 | VM | 1 | Check terminal | _ | _ | Check terminal VM | | |
| 16 | GND | 1 | Check terminal | _ | _ | Check terminal GND | | |
| 17 | VCC | 1 | Check terminal | _ | _ | Check terminal VCC | | |
| 18 | VREF | 1 | Check terminal | | _ | Check terminal VREF | | |
| 19 | IN1 | 1 | Check terminal | _ | _ | Check terminal IN1 | | |
| 20 | IN2 | 1 | Check terminal | _ | _ | Check terminal IN2 | | |
| 21 | RS | 1 | Check terminal | _ | _ | Check terminal RS | | |
| 22 | OUT1 | 1 | Check terminal | _ | _ | Check terminal OUT1 | | |
| 23 | OUT2 | 1 | Check terminal | - | _ | Check terminal OUT2 | | |
| 24 | GND | 1 | Check terminal | ı | _ | Check terminal GND | | |
| 25 | GND | 1 | Check terminal | ı | _ | Check terminal GND | | |
| 26 | VR1 | 1 | 100kΩ | 1 | _ | Variable Resistor | | |
| 27 | C1 | 0 | Not mount | _ | _ | Chip capacitor | | 1 |
| 28 | C2 | 0 | Not mount | _ | _ | Chip capacitor | | √ |
| 29 | C3 | 0 | Not mount | | _ | Chip capacitor | | 1 |
| 30 | | | | | | | | |

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